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(54) Title: HEAT PIPE THERMAL MANAGEMENT APPARATUS			
(57) Abstract <p>A thermal management apparatus comprising a heat pipe component in thermal communication with a molded heat sink component. In a preferred embodiment, the heat sink comprises a filled, thermally conductive, liquid crystal polymer or thermoset resin. Preferably, the thermal management apparatus will be formed as a unitary structure by an insert molding operation.</p>			